

a1
an insulating resin layer directly covering a remaining portion of said major surface of said insulating substrate and said plural electrodes except surfaces of said plural electrodes so as to anchor said plural electrodes to said insulating substrate.

a2
3. (Amended) The array of electrodes as set forth in claim [2] 1, in which said conductive paste is selected from the group consisting of silver paste, gold paste, copper paste and solder paste.

a3
6. (Amended) The array of electrodes as set forth in claim 5, in which said insulating resin layer is selected from the group consisting of a polyimide resin, an epoxy resin, a phenol resin, an acrylic resin and a silicone resin.

a4
10. (Amended) The array of electrodes as set forth in claim 1, in which said plural electrodes are formed of a heat-fusible conductive material, and are directly fixed to said conductive pattern by means of [pieces] bits of said heat-fusible conductive material fused therefrom.

11. (Amended) The array of electrodes as set forth in claim 10, in which said heat-fusible conductive material [is] comprises solder.

REMARKS

The Specification has been amended to correct minor clerical errors, and to employ more idiomatic English. No new matter has been entered by any of the foregoing amendments.